

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Takashi NAKANISHI	02/09/2009
Masato KIKUCHI	02/10/2009
Shunsuke MOCHIZUKI	02/13/2009
Masahiro YOSHIOKA	02/17/2009
Ryosuke ARAKI	02/19/2009
Masaki HANDA	02/19/2009
Hiroshi ICHIKI	02/17/2009
Tetsujiro KONDO	02/23/2009

RECEIVING PARTY DATA

Name:	SONY CORPORATION
Street Address:	1-7-1 Konan, Minato-ku
City:	Tokyo
State/Country:	Japan
Postal Code:	108-0075

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12396770

CORRESPONDENCE DATA

Fax Number: (703)413-2220

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: (703) 413-3000

Email: bsanchez@oblon.com

Correspondent Name: Oblon, Spivak, et al.

Address Line 1: 1940 Duke Street

Address Line 4: Alexandria, VIRGINIA 22314

ATTORNEY DOCKET NUMBER:

339061US8

PATENT

500796669

REEL: 022340 FRAME: 0487

OP \$40.00 12396770

NAME OF SUBMITTER:

Beatriz Sanchez

Total Attachments: 3

source=339061USassignment#page1.tif

source=339061USassignment#page2.tif

source=339061USassignment#page3.tif

PATENT

REEL: 022340 FRAME: 0488

Docket Number: _____

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in MODULATING DEVICE AND METHOD, DEMODULATING DEVICE AND METHOD, PROGRAM, AND RECORDING MEDIUM

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: _____, Filing Date: _____.

This assignment executed on the dates indicated below.

Takashi NAKANISHI
Name of first or sole inventor

February 9, 2007
Execution date of U.S. Patent Application

Tokyo, Japan
Residence of first or sole inventor

Takashi Nakanishi
Signature of first or sole inventor

February 9, 2007
Date of this assignment

Masato KIKUCHI	February 10, 2009
Name of second inventor	Execution date of U.S. Patent Application
Tokyo, Japan	
Residence of second inventor	
Masato Kikuchi	February 10, 2009
Signature of second inventor	Date of this assignment

Shunsuke MOCHIZUKI	February 13, 2009
Name of third inventor	Execution date of U.S. Patent Application
Tokyo, Japan	
Residence of third inventor	
Shunsuke Mochizuki	February 13, 2009
Signature of third inventor	Date of this assignment

Masahiro YOSHIOKA	February 17, 2009
Name of fourth inventor	Execution date of U.S. Patent Application
Tokyo, Japan	
Residence of fourth inventor	
Masahiro Yoshioka	February 17, 2009
Signature of fourth inventor	Date of this assignment

Ryosuke ARAKI	February 19, 2009
Name of fifth inventor	Execution date of U.S. Patent Application
Tokyo, Japan	
Residence of fifth inventor	
Ryosuke Araki	February 19, 2009
Signature of fifth inventor	Date of this assignment

Masaki HANDA

February 19, 2009

Name of sixth inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of sixth inventor

Masaki Handa

February 19, 2009

Signature of sixth inventor

Date of this assignment

Hiroshi ICHIKI

February 17, 2009

Name of seventh inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of seventh inventor

Hiroshi Ichiki

February 17, 2009

Signature of seventh inventor

Date of this assignment

Tetsujiro KONDO

Feb. 23, 2009

Name of eighth inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of eighth inventor

Tetsujiro Kondo

Feb. 23, 2009

Signature of eighth inventor

Date of this assignment

Name of ninth inventor

Execution date of U.S. Patent Application

Residence of ninth inventor

Signature of ninth inventor

Date of this assignment